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#### FDT459N

#### N-Channel Enhancement Mode Field Effect Transistor

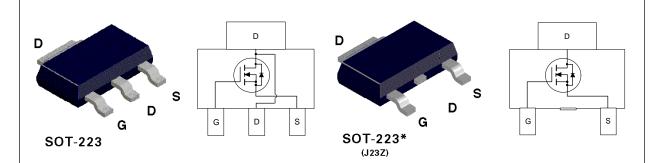
#### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance, provide superior switching performance. These products are well suited to low voltage, low current applications such as notebook computer power management, battery powered circuits, and DC motor control.

#### **Features**

- 6.5 A, 30 V.  $R_{DS(ON)} = 0.035\Omega$  @  $V_{GS} = 10$  V  $R_{DS(ON)} = 0.055~\Omega$  @  $V_{GS} = 4.5$  V.
- High density cell design for extremely low R<sub>DS(ON)</sub>.
- High power and current handling capability in a widely used surface mount package.





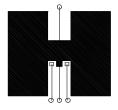
#### **Absolute Maximum Ratings** $T_A = 25^{\circ}\text{C}$ unless otherwise noted

Parameter		FDT459N	Units
Drain-Source Voltage		30	V
Gate-Source Voltage - Continuous		±20	V
Maximum Drain Current - Continuous (Note 1a)		6.5	A
- Pulsed		20	
Maximum Power Dissipation	(Note 1a)	3	W
	(Note 1b)	1.3	
	(Note 1c)	1.1	
Operating and Storage Temperature Range		-55 to 150	°C
L CHARACTERISTICS			
Thermal Resistance, Junction-to-Am	bient (Note 1a)	42	°C/W
Thermal Resistance, Junction-to-Cas	SE (Note 1)	12	°C/W
	Drain-Source Voltage  Gate-Source Voltage - Continuous  Maximum Drain Current - Continuou  - Pulsed  Maximum Power Dissipation  Operating and Storage Temperature  CHARACTERISTICS  Thermal Resistance, Junction-to-Am	Drain-Source Voltage  Gate-Source Voltage - Continuous  Maximum Drain Current - Continuous  - Pulsed  Maximum Power Dissipation  (Note 1a)  (Note 1b)  (Note 1c)  Operating and Storage Temperature Range  CHARACTERISTICS  Thermal Resistance, Junction-to-Ambient (Note 1a)	Drain-Source Voltage         30           Gate-Source Voltage - Continuous         ±20           Maximum Drain Current - Continuous (Note 1a)         6.5           - Pulsed         20           Maximum Power Dissipation (Note 1a) (Note 1b) (Note 1b)         1.3           (Note 1c) (Note 1c)         1.1           Operating and Storage Temperature Range -55 to 150           L CHARACTERISTICS           Thermal Resistance, Junction-to-Ambient (Note 1a)         42

<sup>\*</sup> Order option J23Z for cropped center drain lead.

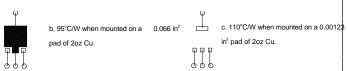
Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAR	ACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		30			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to	I <sub>D</sub> = 250 μA, Referenced to 25 °C		33		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V				1	μA
			T <sub>J</sub> =55°C			10	μA
GSSF	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
GSSR	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHARA	CTERISTICS (Note 2)	·					
/ <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1	1.6	2	V
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp.Coefficient	I <sub>D</sub> = 250 μA, Referenced to	25 °C		-4.2		mV/°C
	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$			0.031	0.035	Ω
			T <sub>J</sub> =125°C		0.044	0.06	
		$V_{GS} = 4.5 \text{ V}, I_{D} = 5.5 \text{ A}$			0.046	0.055	
D(ON)	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$		20			Α
Fs	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 6.5 \text{ A}$			16		S
OYNAMIC C	CHARACTERISTICS						
iss	Input Capacitance	$V_{DS} = 15 \text{ V}, \ V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$			365		pF
oss	Output Capacitance				210		pF
rss	Reverse Transfer Capacitance				70		pF
WITCHING	G CHARACTERISTICS (Note 2)						
O(on)	Turn - On Delay Time	$V_{DD} = 15 \text{ V}, I_{D} = 1 \text{ A},$			5.2	11	ns
	Turn - On Rise Time	$V_{GS} = 10 \text{ V}, \ R_{GEN} = 6 \Omega$			8.2	16	ns
D(off)	Turn - Off Delay Time				6	12	ns
1	Turn - Off Fall Time				16	26	ns
$Q_g$	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_D = 6.5 \text{ A},$ $V_{GS} = 10 \text{ V}$			12	17	nC
$Q_{gs}$	Gate-Source Charge				2.2		nC
$Q_{gd}$	Gate-Drain Charge				3		nC
RAIN-SOU	IRCE DIODE CHARACTERISTICS AND MA	XIMUM RATINGS			ı	ı	
3	Maximum Continuous Drain-Source Diode Forward Current				2.5	Α	
/ <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.5 \text{ A} \text{ (Note 2)}$			0.8	1.2	V

Typical  $R_{_{\theta^{J\!A}}}$  using the board layouts shown below on  $\,$  FR-4 PCB in a still air environment:



a. 42°C/W when mounted on a 1 in² pad of 2oz Cu.





Scale 1: 1 on letter size paper 2. Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2.0\%$ 

<sup>1.</sup>  $R_{g,u}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{g,c}$  is guaranteed by design while  $\boldsymbol{R}_{\text{\tiny BCA}}$  is determined by the user's board design.

#### **Typical Electrical Characteristics**

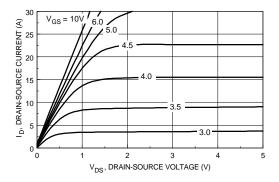


Figure 1. On-Region Characteristics.

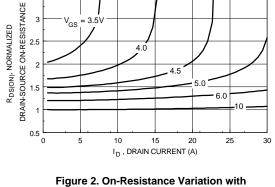


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

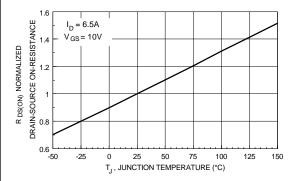


Figure 3. On-Resistance Variation with Temperature.

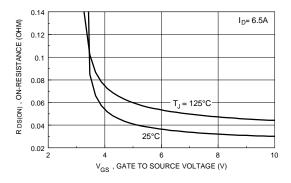


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

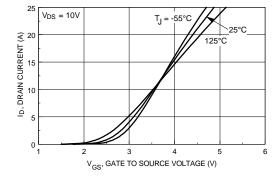


Figure 5. Transfer Characteristics.

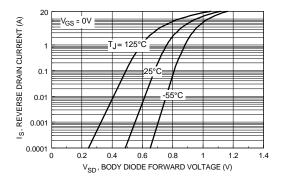


Figure 6. Body Diode Forward Voltage
Variation with Source Current
and Temperature.

#### **Typical Electrical Characteristics**

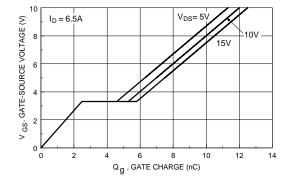


Figure 7. Gate Charge Characteristics.

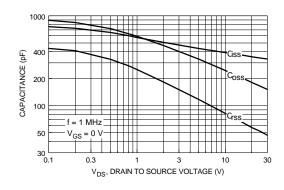


Figure 8. Capacitance Characteristics.

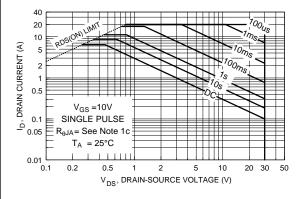


Figure 9. Maximum Safe Operating Area.

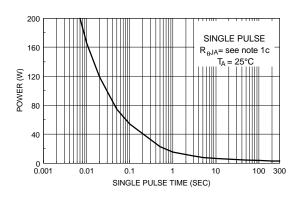


Figure 10. Single Pulse Maximum Power Dissipation.

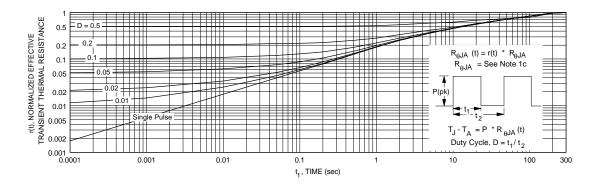


Figure 11. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

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